

INFORMATION DISCLOSURE CITATION

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ATTY DOCKET NO.
YKI-0033-C

SERIAL NO.
10/748,928

Naoaki Komiya et al.

FILING
12/30/2003

GROUP
2821

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
ED	3,869,646	03/04/1975	Kirton et al.	315	246	
	4,459,514	07/10/1984	Morimoto et al.	315	169.1	
	4,704,559	11/03/1987	Suginoya et al.	315	169.1	
	5,670,792	09/23/1997	Utsugi et al.	257	59	
	5,684,365	11/04/1997	Tang et al.	315	169.3	
✓	5,966,189	10/12/1999	Matsuo	349	38	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

T.D		Japanese Notice of Grounds for Rejection for Patent Application Serial No. HEI 11-046741, dated 8/27/2002 with English Translation
T.D		Patent Abstracts of Japan, Publication No. 09-081053, dated 28.03.1997

EXAMINER

Trinh Vo Dinh

DATE CONSIDERED

07/08/2005

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T.D			Japanese Patent Laid Open Publication No. HEI 10-239699, dated 09/11/1998 with English Abstract and partial English translation

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